

Examiner's Copy

AN 107:11597 HCA
TI **Copper**-based alloys for semiconductor lead frames
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SO Jpn. Kokai Tokkyo Koho, 3 pp.
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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 61266540	A2	19861126	JP 1985-108938	19850521
AB	The alloys contain Fe 0.5-3, Ni 0.4-2, P 0.01-0.5, and Sn 0.15-1.5%. The alloys contain uniformly dispersed Ni-P , Fe-P , and Ni-Sn compds., show good elec. cond. and high strength, and can be manufd. at a low cost. A Cu alloy ingot contg. Fe 0.70, Ni 0.62, P 0.06, and Sn 0.21%, prepd. by melting and casting in air was hot rolled, surface ground, and repeatedly cold rolled and process annealed with finishing draft 37% to give a sheet 0.25 mm thick. The sheet showed Vickers hardness 154 and elec. cond. 48% IACS, vs. 172, and 50% IACS for a similarly prepd. sheet of conventional C19500.				